

CC3100 MODBOOST/ TIDC-CC3100MODBOOST  
 BOM Revision - 1.0  
 Date : 11-November -2014

NO.	Qty	Part Reference	Value	Manufacturer	Mfr. PN	Description
1	1	C15	0.1uF	Murata	GRM155R61A104KA01D	CAP CER 100nF 10% 10V SMD 0402 GP/HF X5R 0.5mm
2	14	R15 R22 R29 R36 R37 R38 R44 R46 R48 R65 R66 R73 R81 R82	0ohm	Yageo	RC0402JR-070RL	RES C SMD 0402 0ohm 5% GP/HF
3	2	R12 R14	100ohm	Yageo	RC0402JR-07100RL	RES C SMD 0402 100ohm 5% GP/HF
4	4	R4 R7 R112 R113	100Kohm	Yageo	RC0402FR-07100KL	RES C SMD 0402 100Kohm 1% GP/HF
5	2	C65 C66	100uF	MURATA	GRM32ER60J107ME20L	CAP CER 100uF 20% 6.3V SMD 1210 GP/HF X5R 2.5mm
6	4	R8 R114 R209 R210	10Kohm	Yageo	RC0402FR-0710KL	RES C SMD 0402 10Kohm 1% GP/HF
7	2	C3 C7	10nF	MURATA	GRM155R71H103KA88D	CAP CER 10nF 10% 50V SMD 0402 GP/HF X7R T=0.5mm
8	1	C67	10pF	WALSIN	0402N100C500LT	CAP CER 10pF +-0.25pF 50V SMD 0402 GP/HF NPO 0.5mm
9	1	C64	1.0pF	WALSIN	0402N1R0C500LT	CAP CER 1.0pF +-0.25pF 50V SMD 0402 GP/HF NPO T=0.55mm
10	1	R13	150K	TA-I	RM04FTN1503	EU-GP RES C SMD 0402 150Kohm 1% GP/HF
11	3	SW1 SW2 SW3	SW-4PIN	POWERWAY	DTST-61K-Q	SW TACT 50mA 12V DIP ST GP
12	2	R9 R20	1Kohm	Yageo	RC0402FR-071KL	RES C SMD 0402 1Kohm 1% GP/HF
13	1	C47	1uF	MURATA	GRM155R60J105KE19D	CAP CER 1uF 10% 6.3V SMD 0402 GP/HF X5R 0.5mm
14	1	L1	1uH	MURATA	LQH3NPN1R0MM0L	CN-GP IND WW 1uH 20% 1.4A 0.044ohm SMD GP/
15	1	ANT1	2.4GHz ANT	Taiyo_Yuden	AH316M245001-T	2.4G WIFI chip antenna
17	1	C23	22pF	MURATA	GRM1555C1H220JA01D	CN-GP CAP CER 22pF 5% 50V SMD 0402 GP/HF N
18	1	C4	22uF	MURATA	GRM21BR60J226ME39L	CN-GP CAP CER 22uF 20% 6.3V SMD 0805 GP/HF
18.1	0	C4	22uF	TDK	C2012X5R0J226MT	CN-GP CAP CER 22uF 20% 6.3V SMD 0805 GP/HF
19	1	C17	2.2uF	MURATA	GRM21BR71C225KA12L	CAP CER 2.2uF 10% 16V SMD 0805 GP/HF X7R T=1.25mm
19.1	0	C17	2.2uF	WALSIN	0805B225K160CT	CAP CER 2.2uF 10% 16V SMD 0805 GP/HF X7R T=1.25mm
20	2	R71 R72	270ohm	Yageo/Phycomp.	RC0402JR-07270RL	RES C SMD 0402 270ohm 5% GP/HF
21	1	R78	3.3K	TA-I	RM04JTN332	RES C SMD 0402 3.3Kohm 5% GP/HF
22	1	L4	3.6nH	TAIYO	HK10053N6S-T	IND C 3.6nH 0.3nH 300mA 0.2ohm Q=8 SMD 0402 GP/HF
23	1	R205	330ohm	Yageo/Phycomp.	RC0402FR-07330RL	RES C SMD 0402 330ohm 1% GP/HF
24	2	R77 R84	33k	TA-I	RM04FTN3302	RES C SMD 0402 33Kohm 1% GP/HF
25	1	R21	39K	TA-I	RM04FTN3902	EU-GP RES C SMD 0402 39Kohm 1% GP/HF
26	1	R5	430K	WALSIN	WR04X4303FTL	RES C SMD 0402 430Kohm 1% GP
27	2	FB17 FB18	60R	CHILISIN	UPB160808T-600Y-N	BEAD C 60ohm 25% 4A 0.02ohm SMD 0603 GP/HF
28	1	J8	CON3X1	CVILUX	CH31032V200	HEADER PIN 3P 2.54mm DIP MALE ST GP
29	1	J2	CONN_U.FL	FOXCONN	KK23017-01-7F	HEADER RF 1*1PORT D0.5/D2.0mm SMD MALE ST GP/HF
30	1	U1	TLV62090	TI	TLV62090RGTR	IC DC-DC 2.5~5.5V SMD QFN16 GP TLV62090RGTR
31	1	D8	DIODE	DIODES	B240A-13-F	DIODE SBD 40V 2A SMD SMA GP B240A-13-F DIODES
32	2	J9 J10	Header Male 2x10	Samtec	SSQ-110-03-G-D	
34	2	J5 J6	JUMPER MALE	CVILUX	CH31022V202	HEADER PIN 1*2P 2.54mm DIP MALE ST GP
35	1	D6	LED_Green	LITEON	LTST-C190KGKT	LED CHIP 35mcd G 571nm 2P SMD 1.6*0.8mm GP/HF LTST-C190KGKT
36	1	D1	LED_Orange	LITEON	LTST-C190KFKT	LED CHIP 60mcd O 605nm 2P SMD 1.6*0.8mm GP/HF LTST-C190KFKT
37	1	D5	LED_Red	LITEON	LTST-C190KRKT	LED CHIP 45~180mcd R 624~638nm 2P SMD 1.6*0.8mm GP/HF
38	1	J7	USB-MicroB	POWERWAY	SUA-160M3B-L2E-TR1	CONN MICRO USB B 5PIN 0.65mm SMD FEMALE RT GP
39	1	J3	RF Connector	MURATA	MM8030-2610RJ3	HEADER RF 1*1PORT D=0.5/1.35mm SMD FEMALE ST GP
40	2	Q7 Q8	BSS138LT3G	On Semi	BSS138LT3G	MOSFET N-CH 50V 200MA SOT-23
41	3		JUMPER FEMALE	FOXCONN	SI2520H-A0	CONN JUMPER 2P 2.54mm FEMALE RT GP
42	1	PCB	PCB	ZHENDING/APCB	307.00587.025	PCB 2L OSP REV.025 8PCS GP/HF 43.18*50.8mm 95.1200T00
43	0.2		SOLDER PASTE	KOKI	S3X58-M500	CN-GP SOLDER PASTE S3X58 M500 GP/HF
43.1	0		SOLDER PASTE	KOKI	S01X7C58-M500	CN-GP SOLDER PASTE S01X7C58-M500 GP/HF
44	2	D3 D4	DIODE	On Semi	MBR130T1G	DIODE SBD 30V 1A SMD SOD123 GP

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